

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

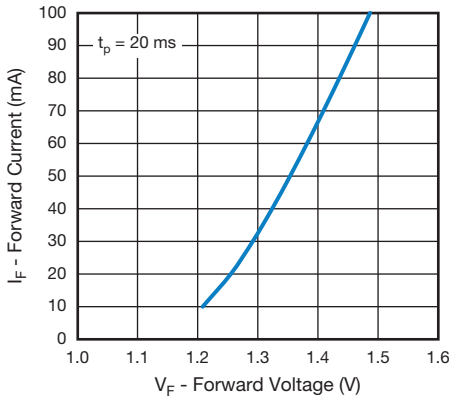


Fig. 4 - Forward Current vs. Forward Voltage

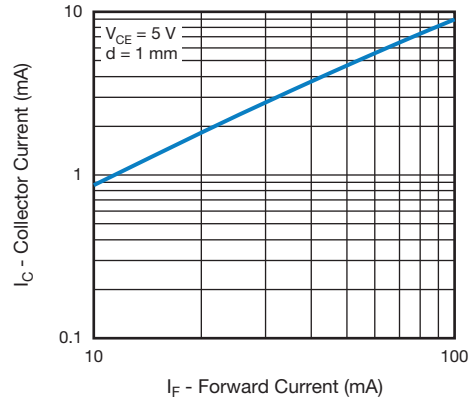


Fig. 7 - Collector Current vs. Forward Current

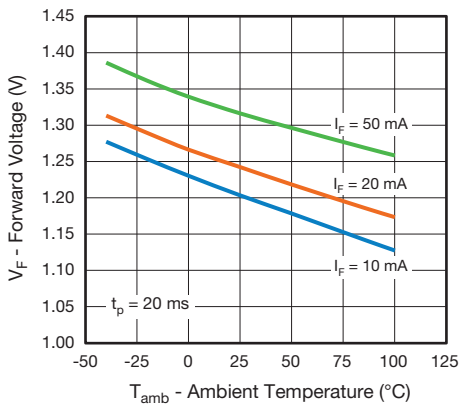


Fig. 5 - Forward Voltage vs. Ambient Temperature

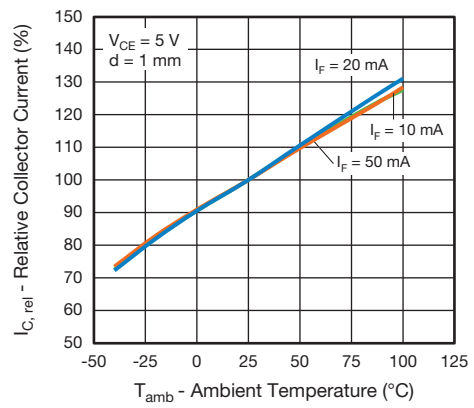


Fig. 8 - Relative Collector Current vs. Ambient Temperature

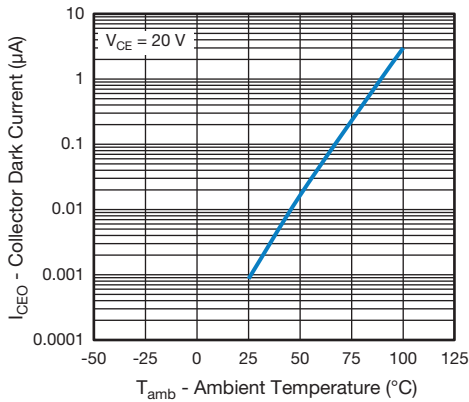


Fig. 6 - Collector Dark Current vs. Ambient Temperature

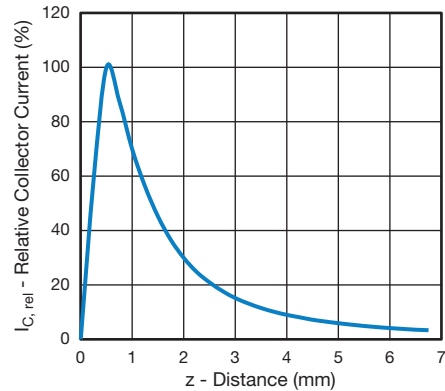


Fig. 9 - Relative Collector Current vs. Distance

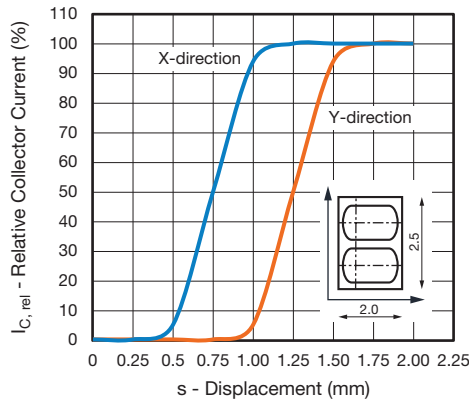


Fig. 10 - Relative Collector Current vs. Displacement

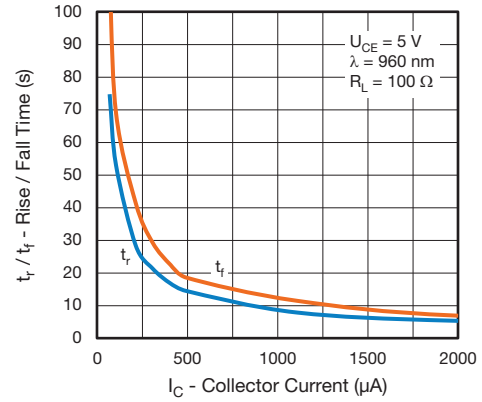


Fig. 11 - Rise / Fall Time vs. Collector Current

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 4

Floor life: 72 h

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, $\text{RH} < 60\%$

DRYING

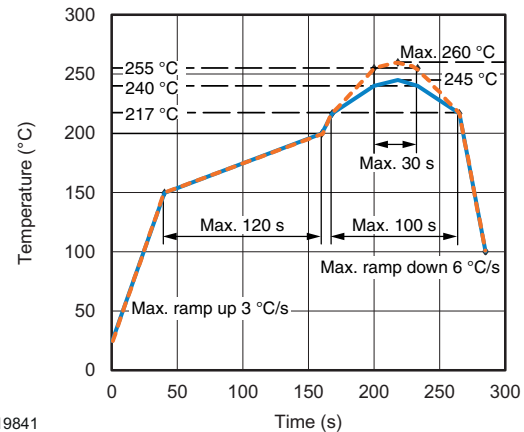
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at $40\text{ }^{\circ}\text{C}$ (+ $5\text{ }^{\circ}\text{C}$), $\text{RH} < 5\%$

or

96 h at $60\text{ }^{\circ}\text{C}$ (+ $5\text{ }^{\circ}\text{C}$), $\text{RH} < 5\%$

REFLOW SOLDER PROFILE



19841

Fig. 12 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020